

FDPF320N06L

N-Channel PowerTrench® MOSFET

60 V, 21 A, 25 mΩ



Features

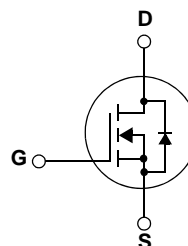
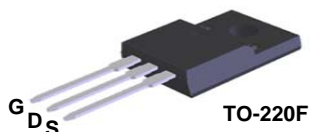
- $R_{DS(on)} = 20\text{ m}\Omega$ (Typ.)@ $V_{GS} = 10\text{ V}$, $I_D = 21\text{ A}$
- $R_{DS(on)} = 23\text{ m}\Omega$ (Typ.)@ $V_{GS} = 5\text{ V}$, $I_D = 17\text{ A}$
- Low Gate Charge (Typ. 23.2 nC)
- Low C_{rss} (Typ. 64 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability
- RoHS Compliant

Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- Consumer Appliances
- LCD / LED / PDP TV



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted*

Symbol	Parameter	FDPF320N06L	Unit
V_{DSS}	Drain to Source Voltage	60	V
V_{GSS}	Gate to Source Voltage	± 20	V
I_D	Drain Current	- Continuous ($T_C = 25^\circ\text{C}$)	21
		- Continuous ($T_C = 100^\circ\text{C}$)	15
I_{DM}	Drain Current	- Pulsed (Note 1)	84
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	66
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6.0
P_D	Power Dissipation	($T_C = 25^\circ\text{C}$)	26
		- Derate above 25°C	0.17
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDPF320N06L	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	5.8	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDPF320N06L	FDPF320N06L	TO-220F	-	-	50

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	60	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$, Referenced to 25°C	-	0.04	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 48\text{V}, T_C = 150^\circ\text{C}$	-	-	1 500	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	μA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.0	-	2.5	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 21\text{A}$ $V_{GS} = 5\text{V}, I_D = 17\text{A}$	-	20 23	25 38	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 21\text{A}$	-	34	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	1105	1470	pF
C_{oss}	Output Capacitance		-	115	150	pF
C_{riss}	Reverse Transfer Capacitance		-	64	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{GS} = 10\text{V}$	-	23.2	30.2	nC
$Q_{g(tot)}$	Total Gate Charge at 5V	$V_{GS} = 5\text{V}$	-	12.7	16.5	nC
Q_{gs}	Gate to Source Gate Charge	$V_{DS} = 48\text{V}$ $I_D = 21\text{A}$ (Note 4)	-	3.4	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	6.3	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30\text{V}, I_D = 21\text{A}$ $V_{GS} = 5\text{V}, R_{GEN} = 4.7\Omega$ (Note 4)	-	16	42	ns
t_r	Turn-On Rise Time		-	34	78	ns
$t_{d(off)}$	Turn-Off Delay Time		-	27	64	ns
t_f	Turn-Off Fall Time		-	8	26	ns
ESR	Equivalent Series Resistance (G-S)	$f = 1\text{MHz}$	-	2	-	Ω

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	21	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	84	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 21\text{A}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_{SD} = 21\text{A}, V_{DD} = 48\text{V}$	-	27	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt = 100\text{A}/\mu\text{s}$	-	23	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L = 1\text{mH}, I_{AS} = 11.5\text{A}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 21\text{A}, di/dt \leq 200\text{A}/\mu\text{s}, V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

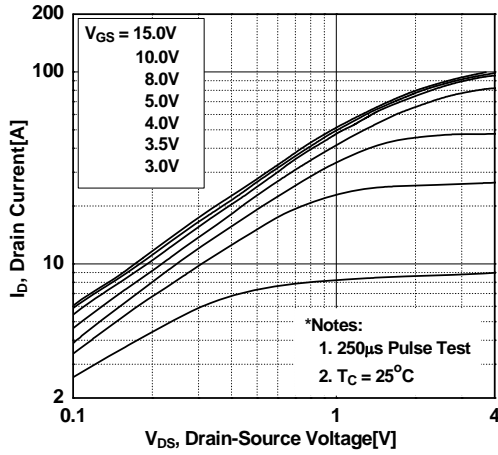


Figure 2. Transfer Characteristics

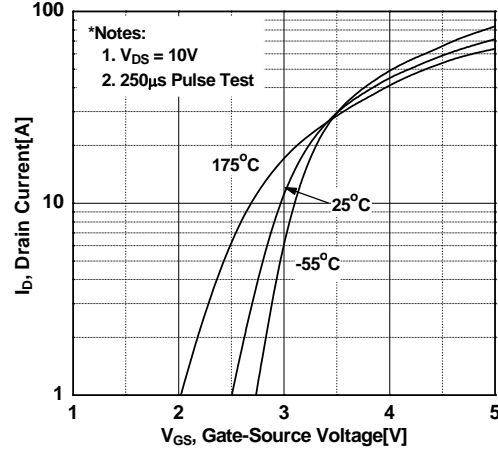


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

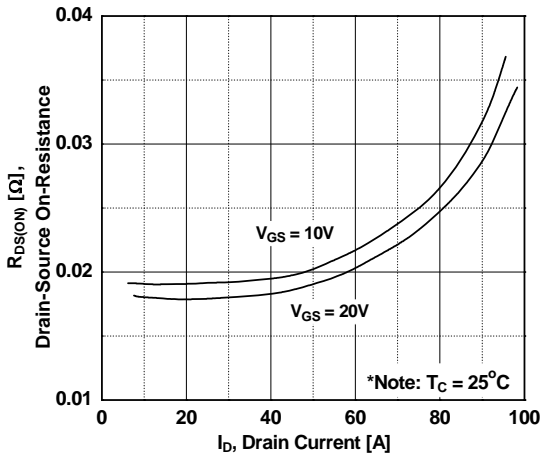


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

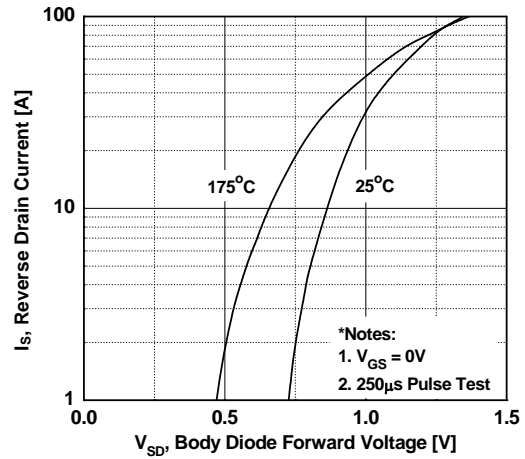


Figure 5. Capacitance Characteristics

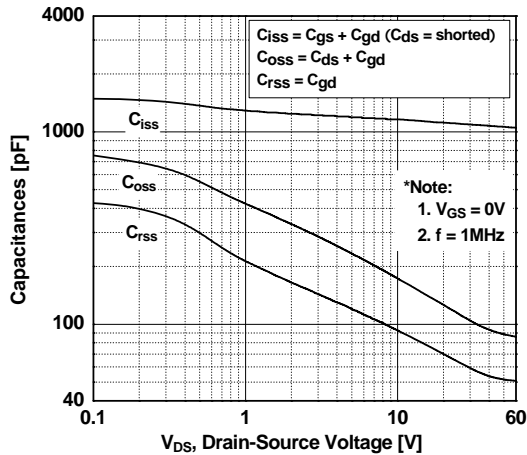
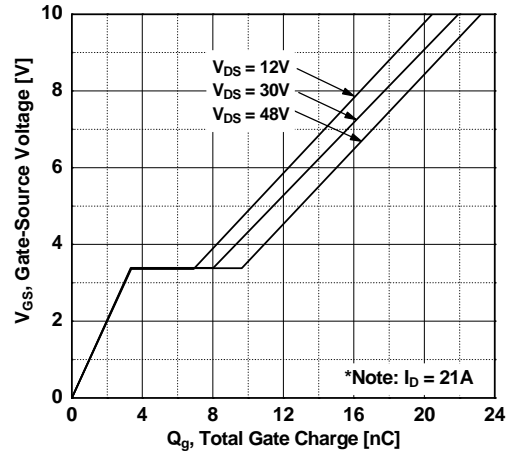


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

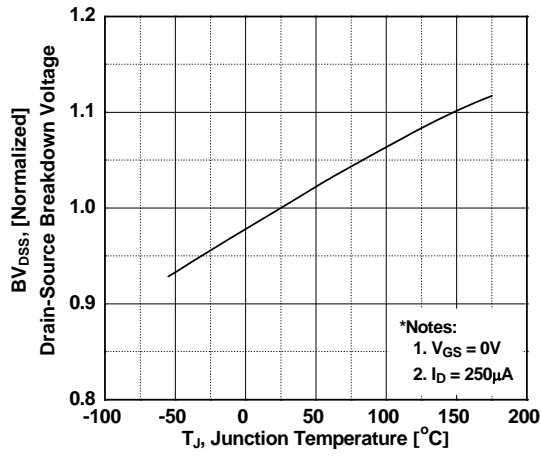


Figure 8. On-Resistance Variation vs. Temperature

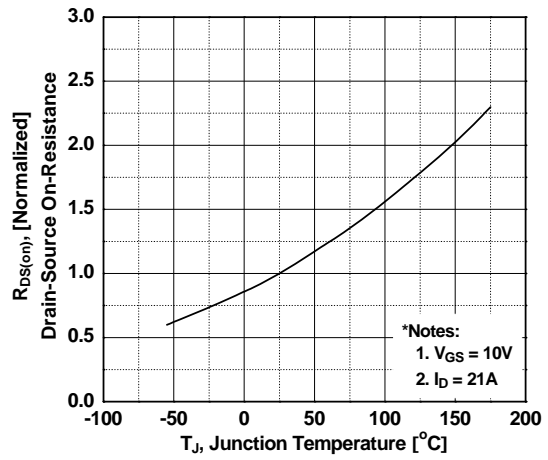


Figure 9. Maximum Safe Operating Area vs. Case Temperature

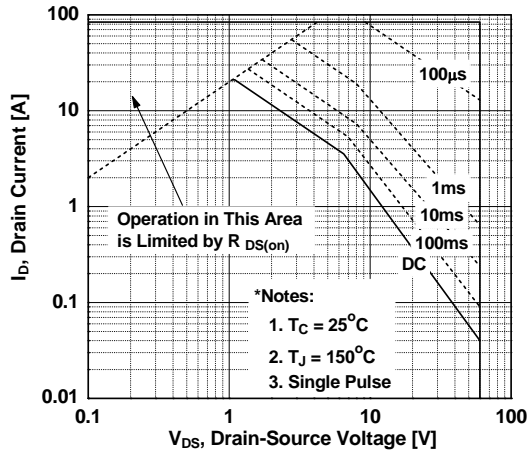


Figure 10. Maximum Drain Current

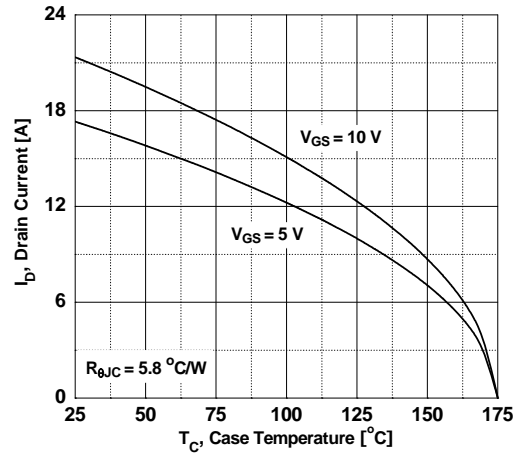
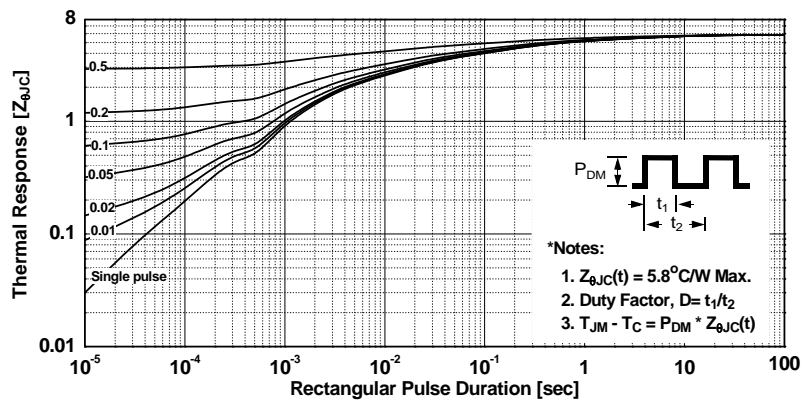
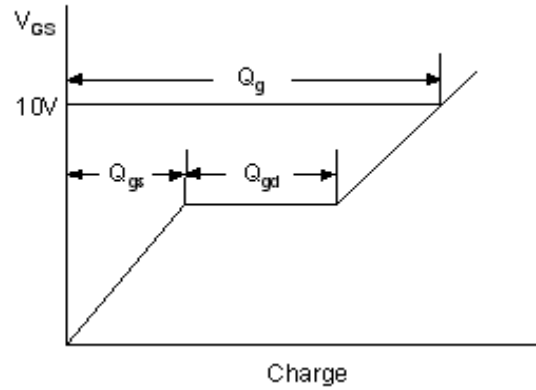
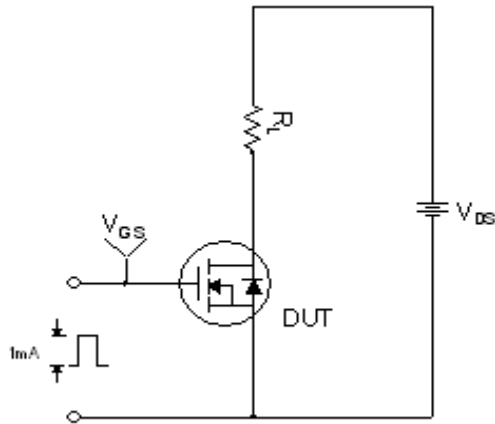


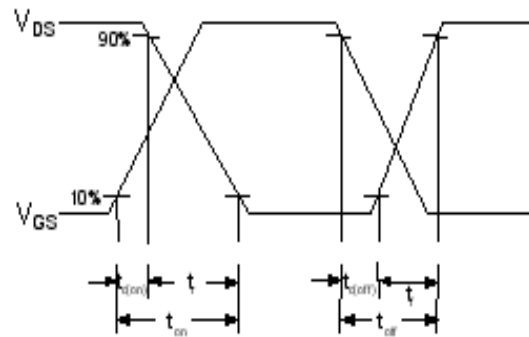
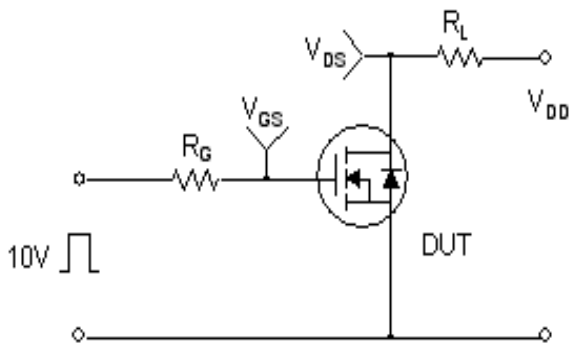
Figure 11. Transient Thermal Response Curve



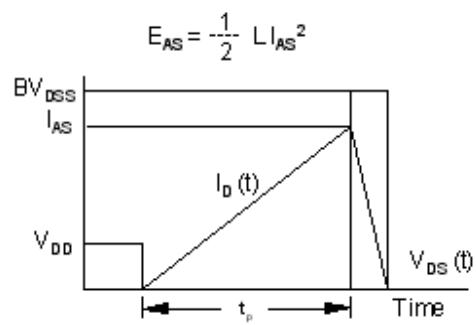
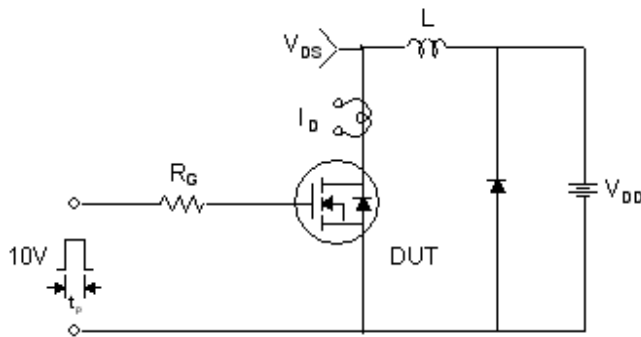
Gate Charge Test Circuit & Waveform



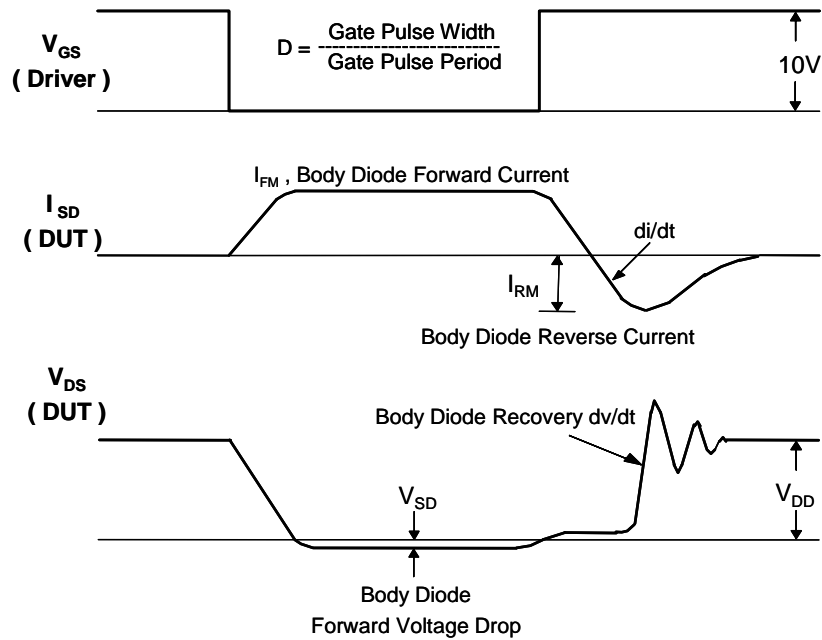
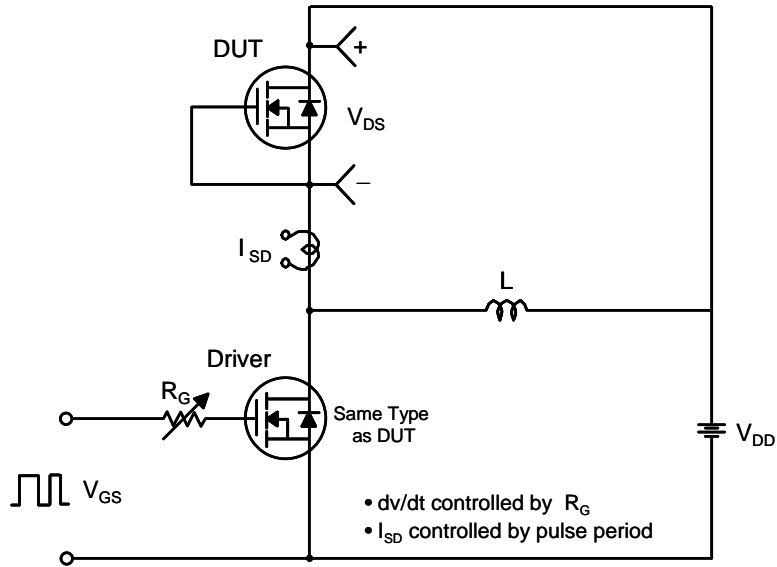
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

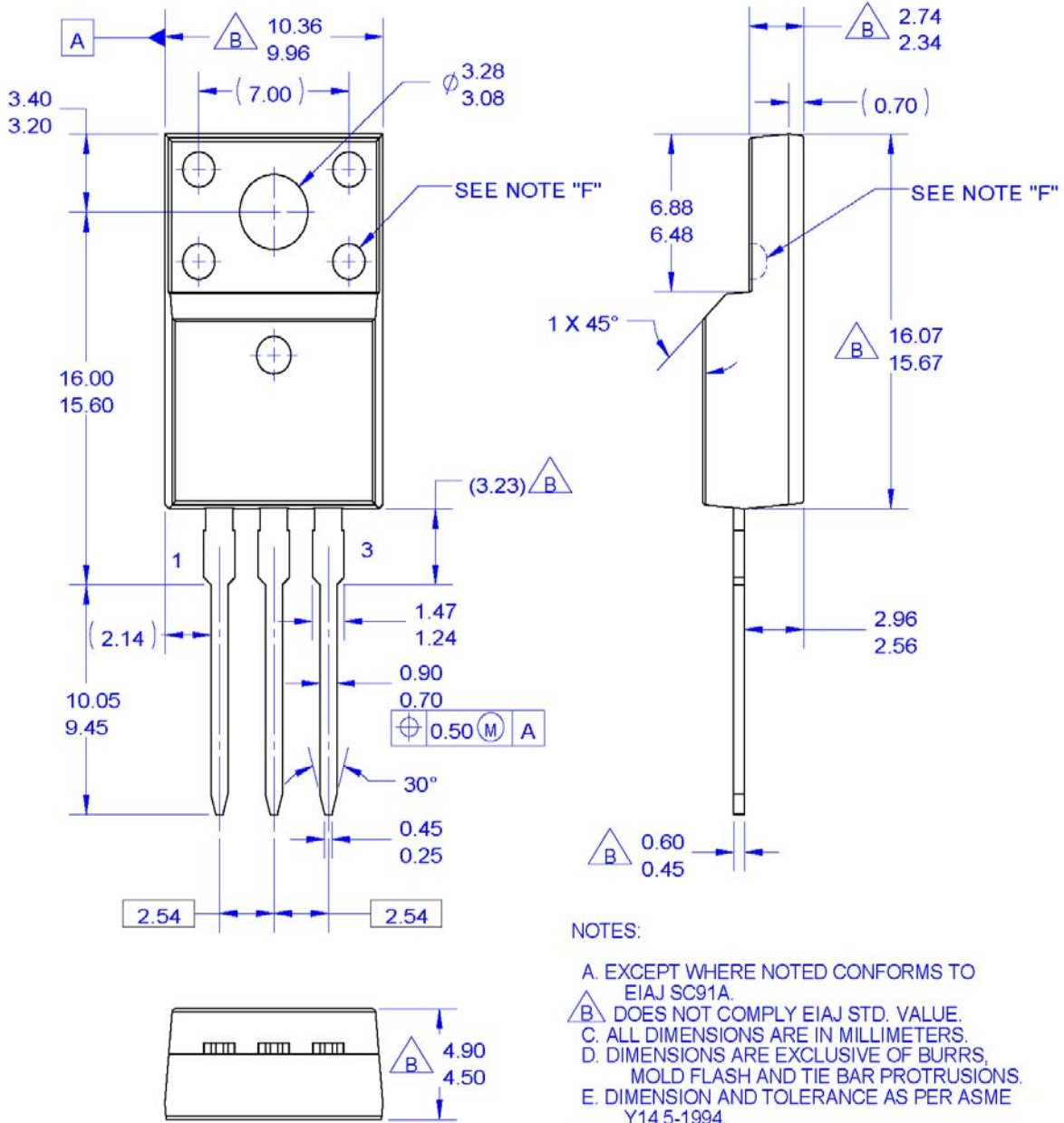


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

TO-220M03






- NOTES:
- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.
 - B. DOES NOT COMPLY EIAJ STD. VALUE.
 - C. ALL DIMENSIONS ARE IN MILLIMETERS.
 - D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
 - E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
 - F. OPTION 1 - WITH SUPPORT PIN HOLE.
OPTION 2 - NO SUPPORT PIN HOLE.
 - G. DRAWING FILE NAME: TO220M03REV3

Dimensions in Millimeters



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| AccuPower™ | F-PFST™ | PowerXS™ | E SYSTEM®* |
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| CorePLUS™ | Green FPS™ | Quiet Series™ | TinyLogic® |
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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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